

IN THE CLAIMS

Please amend the following claims.

1-29 (Cancelled)

30. (Currently amended) A method of forming a semiconductor device comprising:

- forming a gate electrode having a first thickness on a gate dielectric layer formed on a first surface of a substrate;
- forming a pair of source/drain regions on opposite sides of the gate electrode;
- forming a silicon germanium film having a second thickness on the gate electrode;
- forming a silicon germanium film having the second thickness on the source/drain regions;
- forming a silicide layer having a third thickness on the silicon germanium films; and
- forming a pair of sidewall spacers having a first height above the substrate surface on opposite sides of the gate electrode, wherein the first height is greater than the sum of the first, [and] second and third thicknesses on the gate electrode.

31. (Cancelled)

32. (Original) The method of claim 31, wherein the sidewall spacers comprise silicon nitride.

33. (Cancelled)

34. (Cancelled)

35. (Cancelled)

36. (Previously added) The method of claim 30 wherein the gate electrode comprises polysilicon.

cont
C.

37. (Previously added) The method of claim 30 wherein the sidewall spacers are less than 300Å in width.
